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(57) Abstract: The invention provides a chemical-mechanical polishing System for polishing a substrate comprising a polishing component, a water-soluble silicate compound, an oxidizing agent, and water, wherein the pH of the polishing System is 8 to 12. The invention further provides a method of chemically-mechanically polishing a substrate with the aforementioned polishing System. The polishing System provides for reduced friction during polishing of substrates.



WO 2007/149113 A3